

## IEC QUALITY ASSESSMENT SYSTEM (IECQ) covering Electronic Components,

Assemblies, Related Materials and Processes For rules and details of the IECQ visit www.iecq.org

## Schedule of Scope to Certificate of Approval Approved Component - Capability Approval

IECQ Certificate No.: C-IECQ BSI 13.0003

CB Certificate No.: E091/CA

Schedule Number: IECQ-C BSI 13.0003-S Rev No.: 3 Revision Date: 2016/11/24 Page 1 of 1		
Manufacturer:	Merlin Flex Ltd	
Place of Manufacture:	Prospect Way, Hartlepool	
Test Reports:	Issue:	Date:
002 CA Test Report 001	1 1	October 1996 October 2010
Board Types:	Flexible without through connections: Flexible single-sided and double-sided with through connections:	BS CECC 123 400-003 BS CECC 123 500-003
Base Materials:	Polyimide Film Epoxide Woven Glass	Base Stiffener Rigidiser
Board Size:	270 mm x 410 mm Maximum	
Conductors:	Minimum Width: Minimum Spacing:	0.1 mm $\pm$ 0.05 mm 0.1 mm $\pm$ 0.5 mm
Plated Through Hole diameters:	0.42 mm Minimum (finished); for component lead insertion 0.25 mm mounting Minimum (drilled); via hole	
Finishes:	*Bare Copper *Hot Air Solder Levelling Adhesive coated film coverlayer Liquid Photopolymer Solder Mask	

\* These finishes meet the solderability requirements of IEC 60326-2.

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